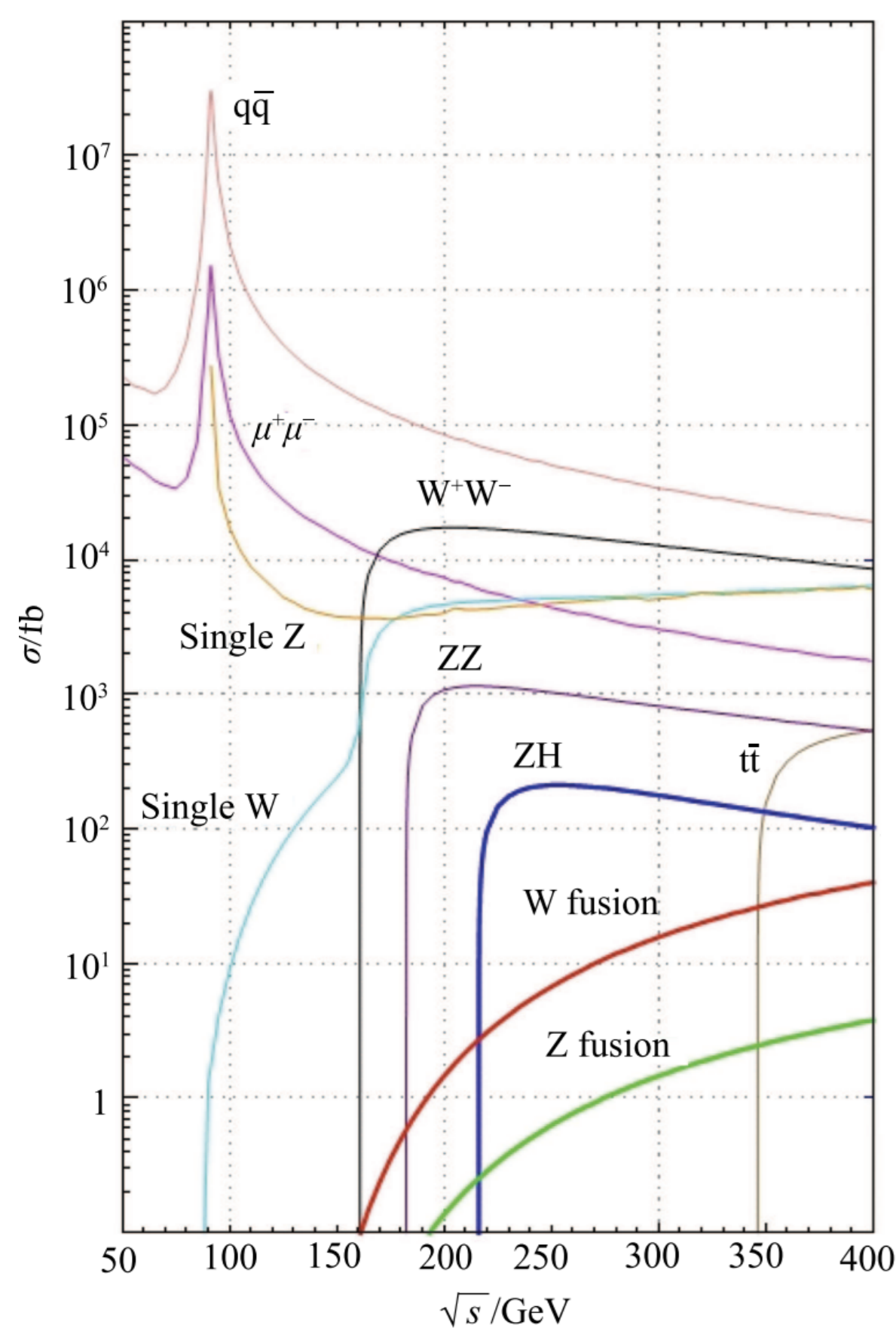


The particle physics community is preparing for the post-LHC era by investigating the feasibility of the *Future Circular Collider* (FCC, [1]): a 90.6 km circumference collider to serve particle physics until the end of the 21st century. FCC-ee will produce intense e^+e^- collisions at energies of 90–365 GeV, making it an EW, Higgs and top factory. Later, the FCC is equipped with 14–20 T magnets to collide hadrons with energies of 80–116 TeV (FCC-hh).

Physics programme at FCC-ee experiments



- EW:** $5 \cdot 10^{12}$ Z, 10^8 WW, 10^6 $t\bar{t}$
- ▶ 20–50 or more improvement in electroweak quantities
 - ▶ Indirect sensitivity to new particles up to 10–70 TeV
- Higgs:** $1.2 \cdot 10^6$ HZ, 75k WW \rightarrow H
- ▶ Higgs width at 1.6%
 - ▶ Higgs couplings at percent to sub-percent precision
- Flavour:** 10^{12} $b\bar{b}$, $c\bar{c}$, $1.7 \cdot 10^{11}$ $\tau\bar{\tau}$
- ▶ $O(10)$ more than Belle-II, not limited to $m(\Upsilon(4S))$

And many many more!

Figure 1: Annihilation cross sections in e^+e^- collisions. Adapted from [2].

FCC-ee detector requirements

e^+ and e^- are **point-like particles** \rightarrow very different than the LHC!

- ▶ Initial E and p known
- ▶ Almost no pile-up, no QCD background

FCC-ee running at the Z pole ($\sqrt{s} = 91.2$ GeV) generates extremely large statistics (*tera-Z factory*). To benefit from this, the systematic uncertainties need to be kept down to 10^{-4} – 10^{-5}

\rightarrow **Stringent requirements on FCC-ee detectors!**

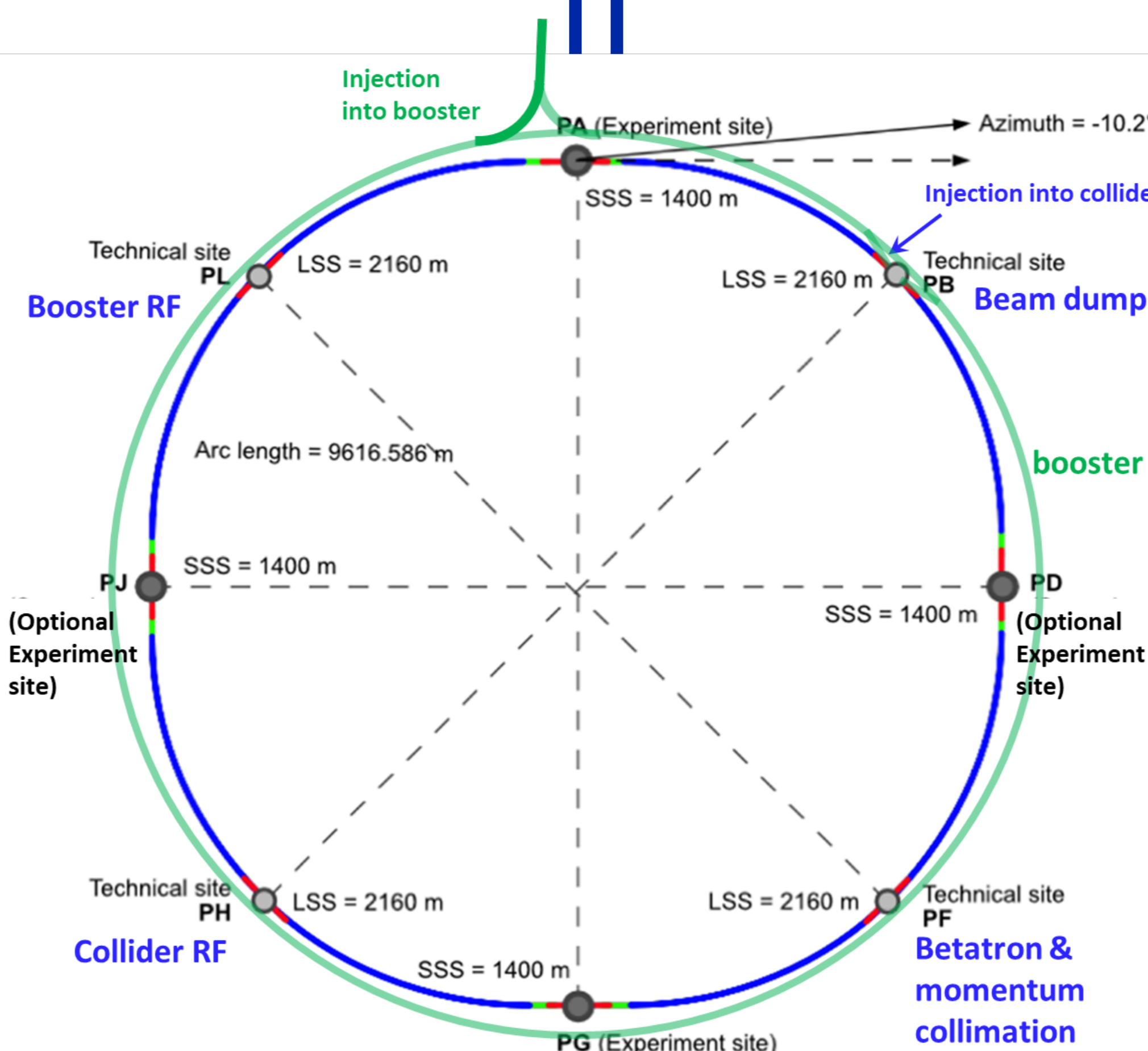
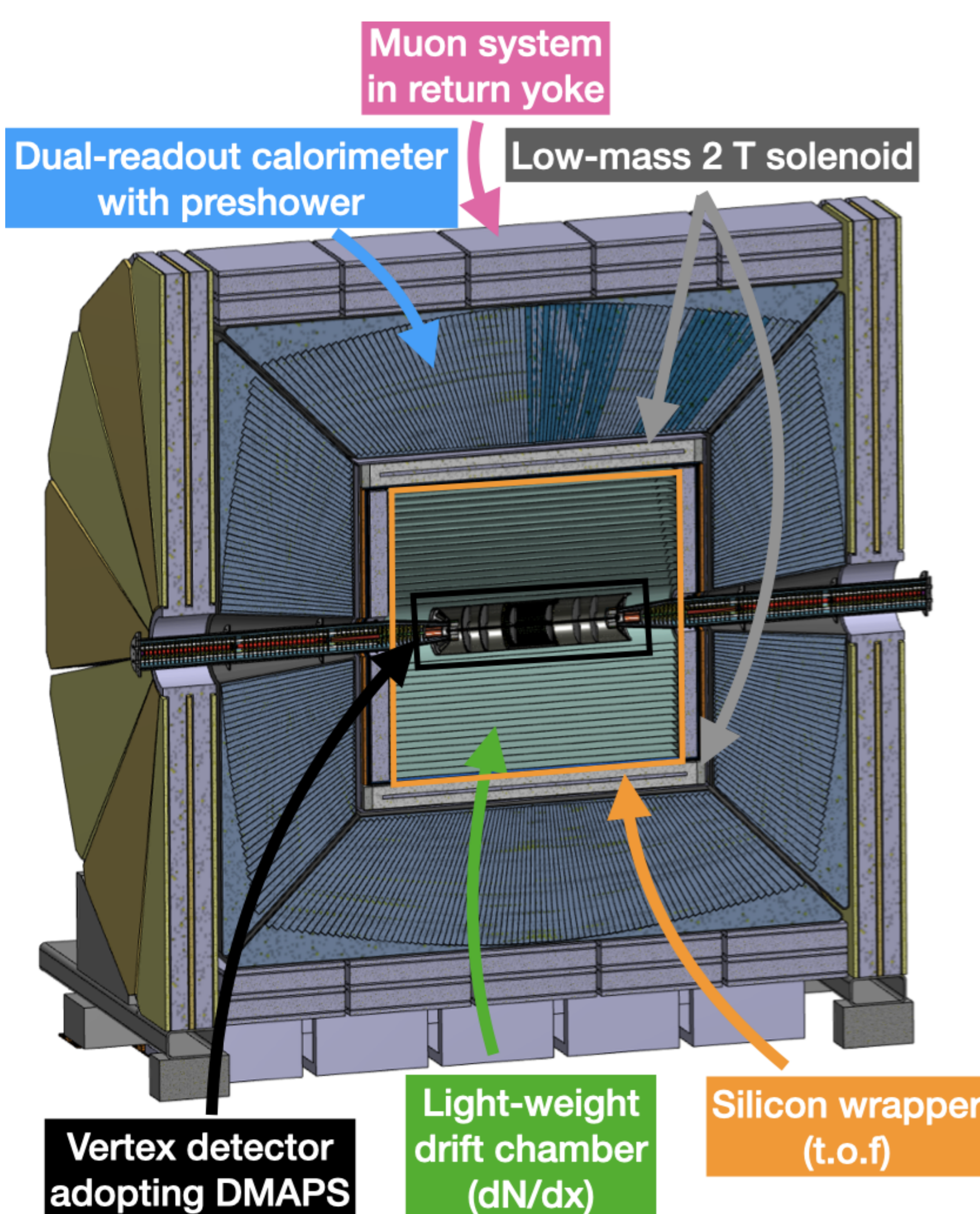
Vertex detector to determine the spatial locations of the interactions

- ▶ Efficient flavour tagging (b/c/g/s)
- ▶ Precise flight distance measurements

Vertex detector requirements:

- ▶ $3 \mu\text{m}$ single-hit resolution
- ▶ $\sigma_{p_T}/p_T^2 \simeq 2 \cdot 10^{-5}/\text{GeV} \rightarrow$ Limit material budget X/X_0 to $\simeq 0.3\%/ \text{layer}$

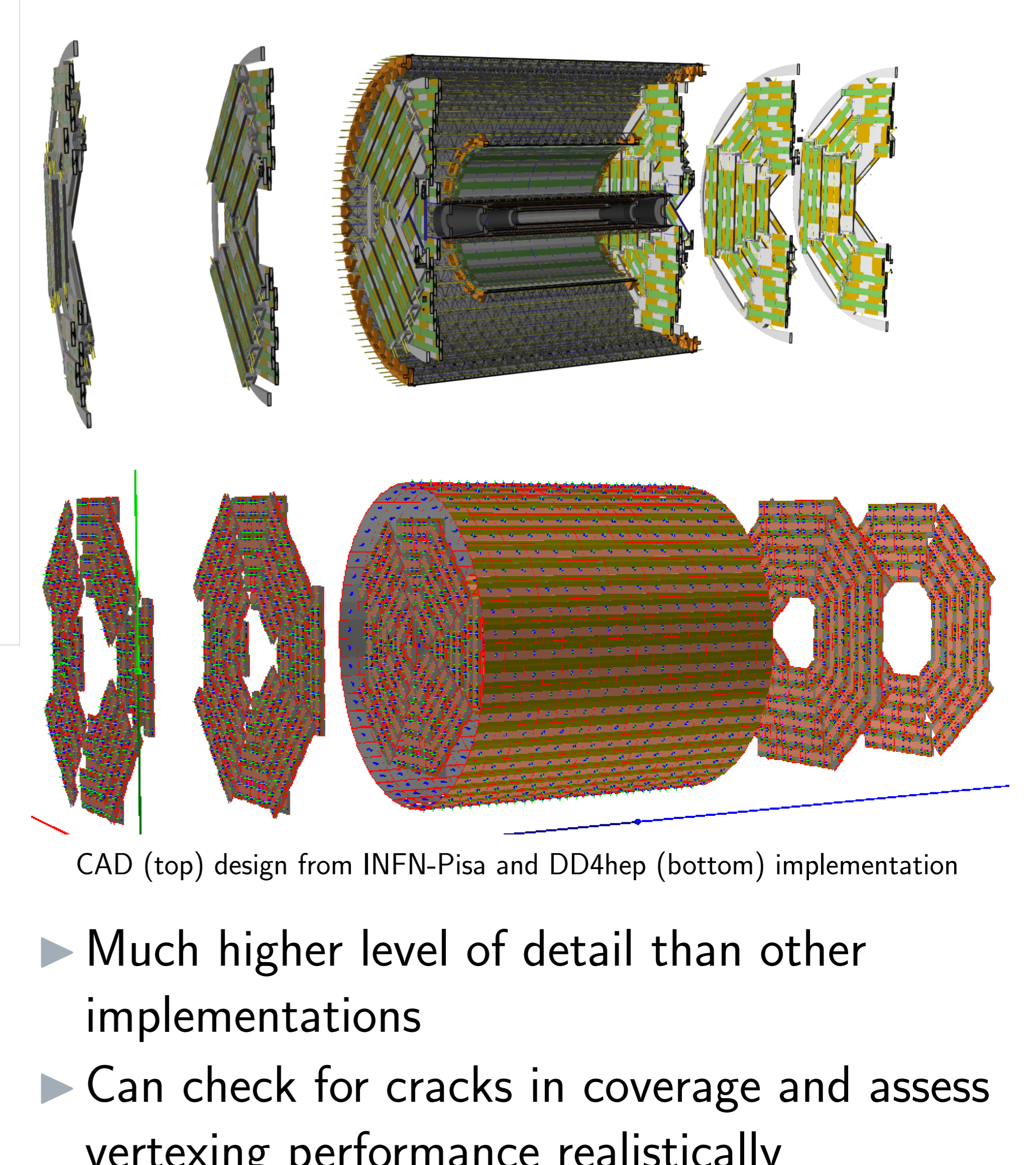
The IDEA detector concept for FCC-ee



Common software vision: Key4hep

- ▶ Adopted by all future collider projects
 - ▶ From generator to analysis
 - ▶ EDM4hep+DD4hep+Gaudi
- Enabling plug-and-play functionality and interface with accelerator components

...and its vertex detector in full simulation



- ▶ Much higher level of detail than other implementations
- ▶ Can check for cracks in coverage and assess vertexing performance realistically

Prospects of wafer-scale DMAPS for FCC-ee vertex detectors

Depleted monolithic active pixel sensors are foreseen by all e^+e^- detector proposals for the vertex detector

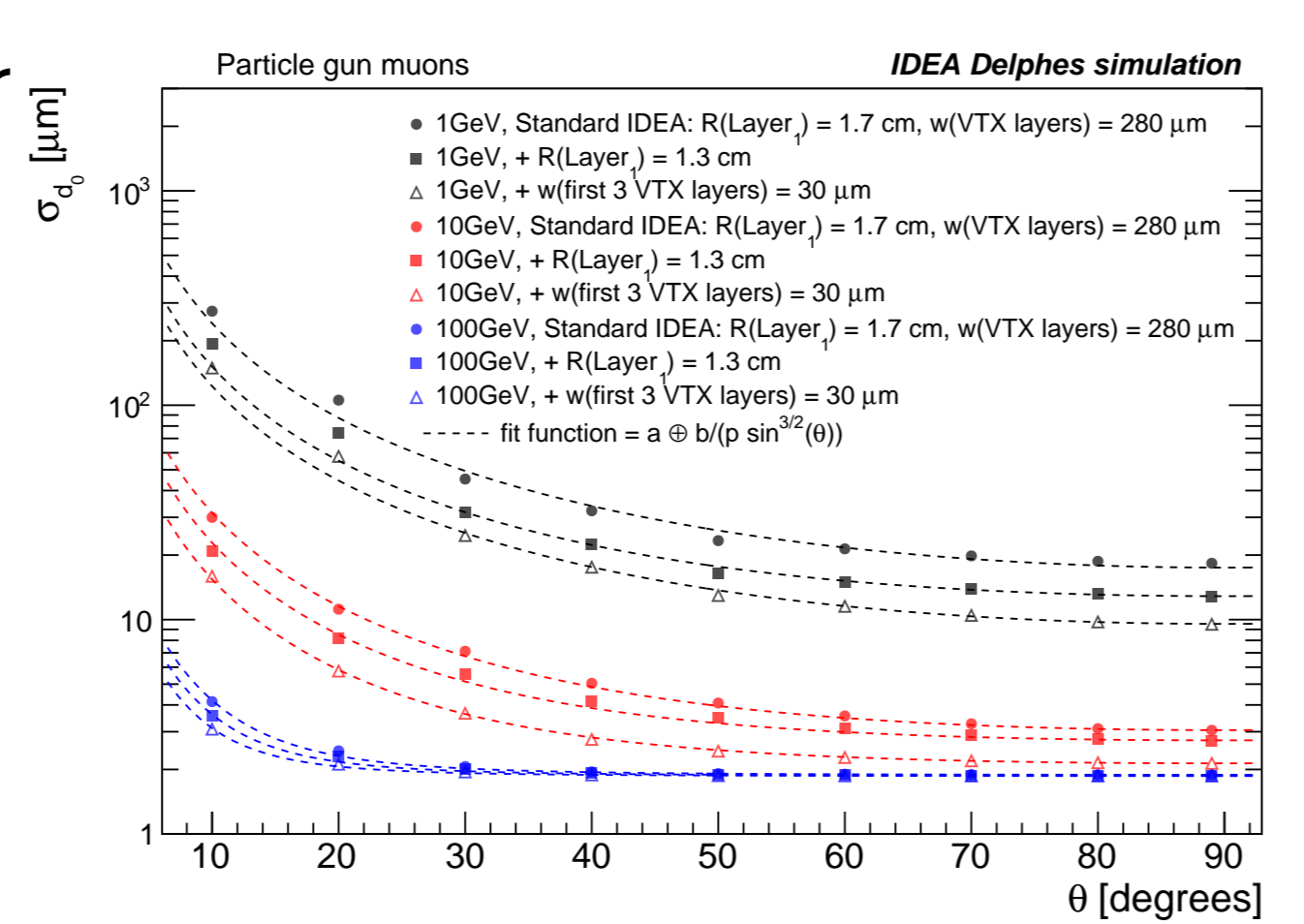
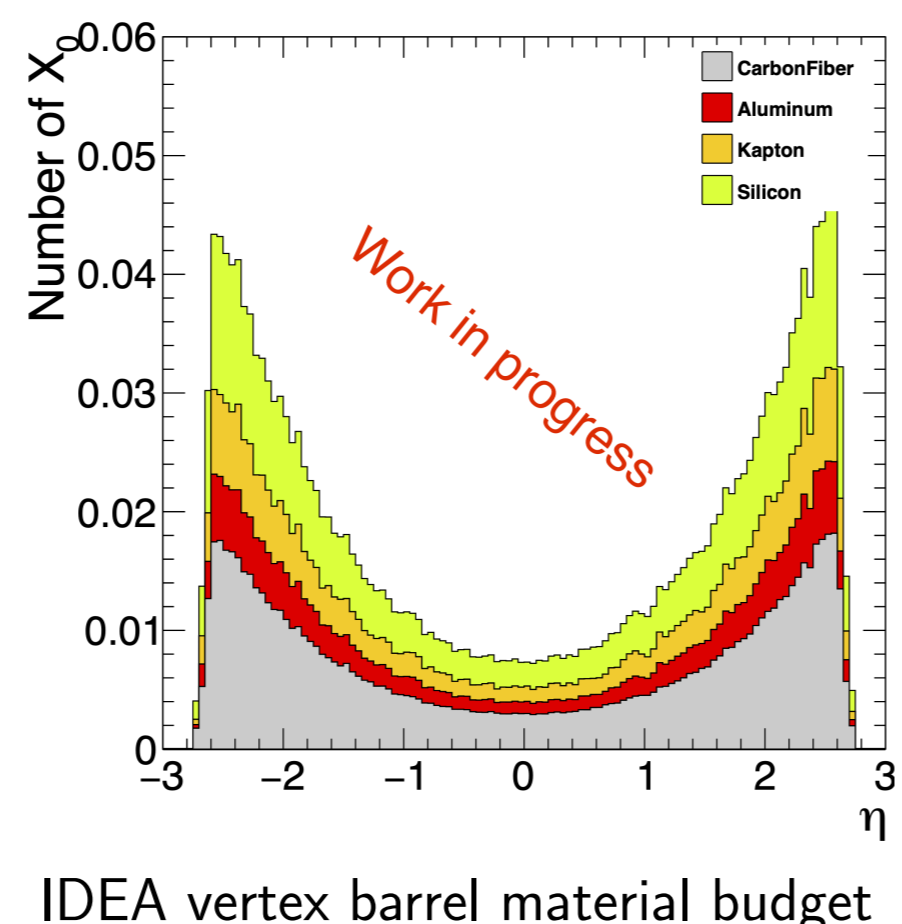
- ▶ Sensor and readout in one silicon die
 - ▶ Sensor (silicon) contributes only a small fraction to total material budget
- \rightarrow Major improvements in tracking and vertexing if X/X_0 is reduced further

65 nm development for ALICE ITS3:

Wafer-scale curved sensors

- ▶ One sensor per half-layer only
 - ▶ Self-supporting, air cooling
- \rightarrow Basically only silicon in vertex

Joined team of ALICE ITS3, CERN R&D and other institutes!



Effect of reduced material budget on d_0 resolution in Delphes fast simulation, L. Freitag (BSc. thesis [3])

R&D on 65 nm DMAPS at UZH

Analog pixel test structure (APTS)

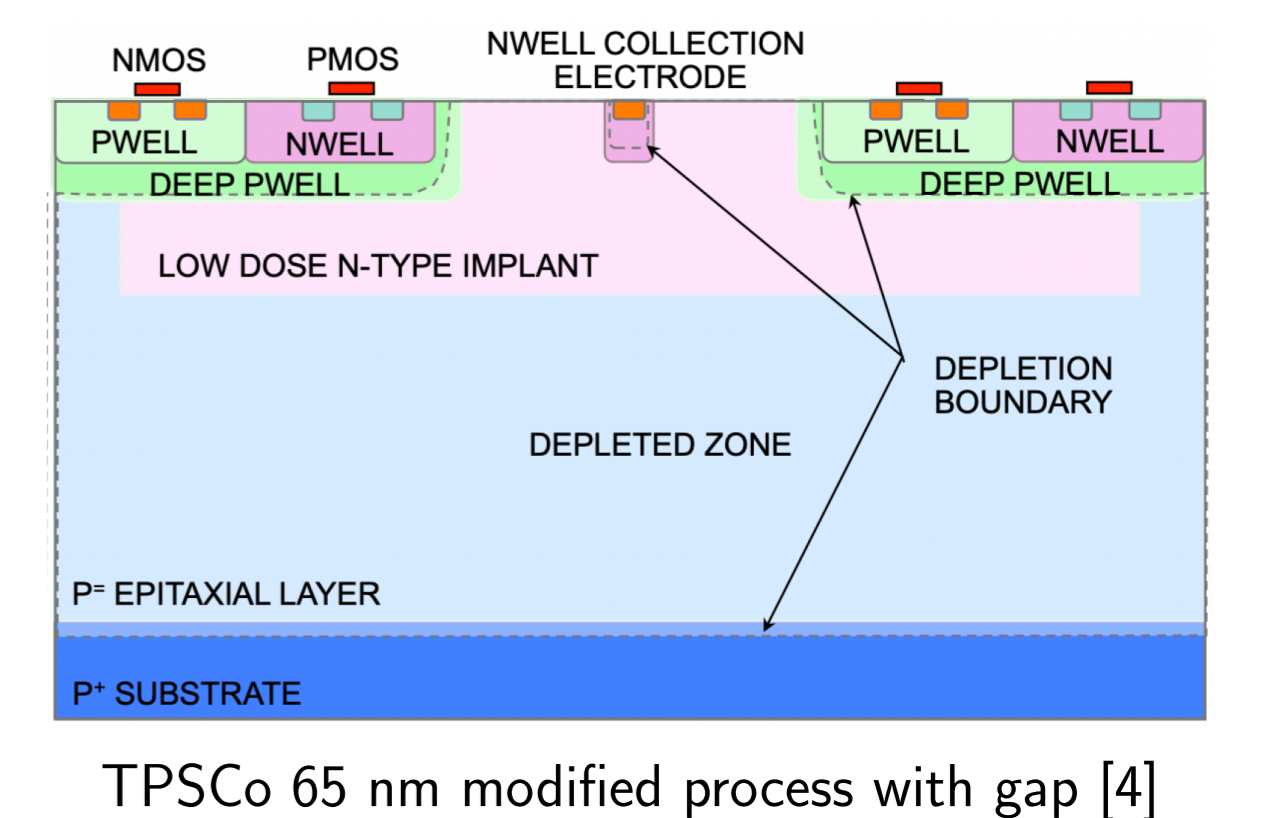
- ▶ 16 pixels, 10 to 25 μm pitch
 - ▶ Analogue readout, different processes
- \rightarrow Test beams, lab tests with Fe-55 source and (eventually) X-ray tube
- Goal: Compare different p-well and n-well collection electrode designs

Circuit Exploratoire (CE-65)

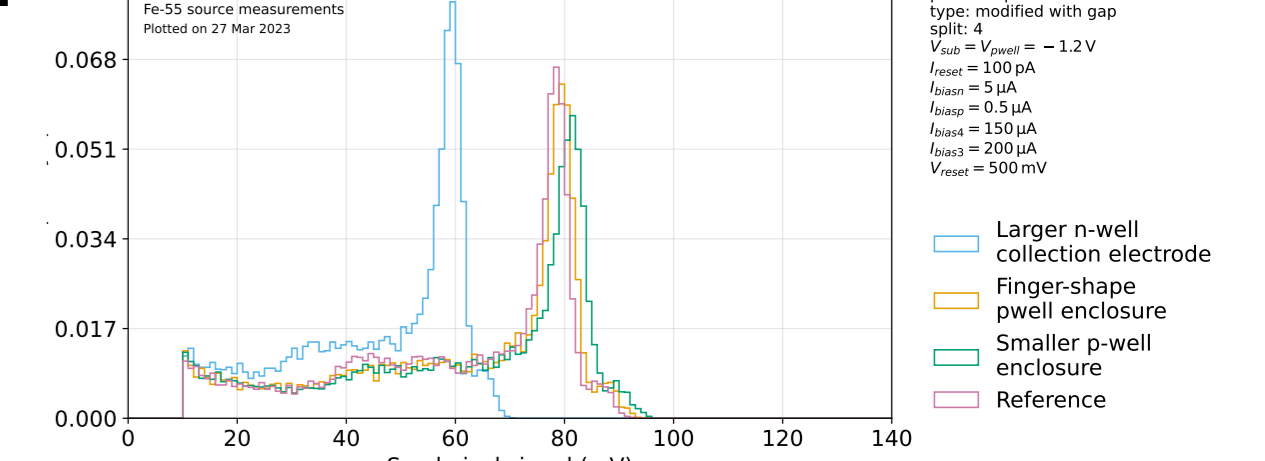
- ▶ 64x32/48x32 pixels, 15/25 μm pitch
- ▶ Digital readout

\rightarrow Test beam this summer, lab test with Fe-55 source

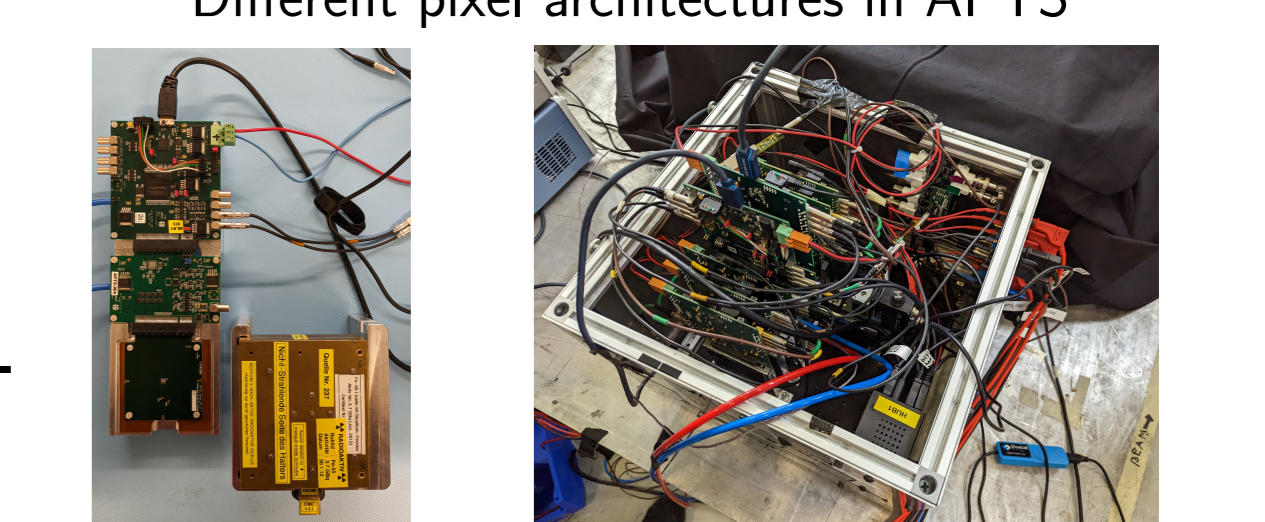
Goal: Long-term development and optimisation towards FCC-ee vertex detectors



TPSCo 65 nm modified process with gap [4]



Different pixel architectures in APTS



Fe-55 test setup ALPIDE telescope

[1] FCC Collaboration, *FCC-ee: The Lepton Collider*, The European Physical Journal Special Topics **228** (2019) 261–623.

[2] X. Mo, G. Li, M.-Q. Ruan, and X.-C. Lou, *Physics cross sections and event generation of e^+e^- annihilations at the CEPC*, Chinese Physics C **40** (2016) 033001.

[3] L. Freitag, *Benefits of Minimizing the Vertex Detector Material Budget at the FCC-ee*, 2023. Presented 01 Feb 2023.

[4] W. Snoeys, et al., *Optimization of a 65 nm CMOS imaging process for monolithic CMOS sensors for high energy physics*, in *Proceedings of Pixel2022*.